Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

MMBTH24

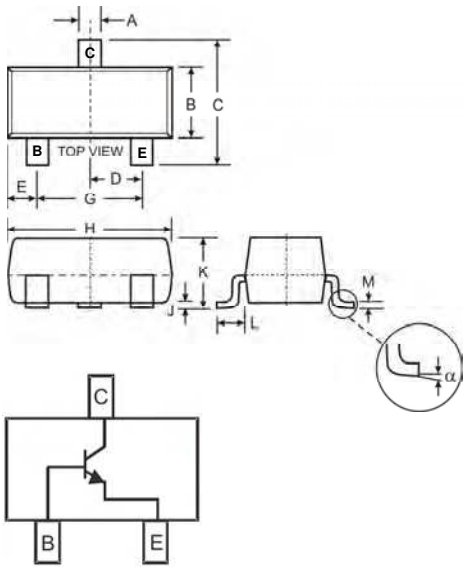
NPN SURFACE MOUNT VHF/UHF TRANSISTOR

Features

- Designed for VHF/UHF Amplifier Applications and High Output VHF Oscillators
- High Current Gain Bandwidth Product
- Ideal for Mixer and RF Amplifier Applications with collector currents in the 100μA - 30 mA Range
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**

Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)



SOT-23		
Dim	**Min**	**Max**
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
E	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	40	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	4.0	V
Collector Current - Continuous (Note 1)	I_C	50	mA
Power Dissipation (Note 1)	P_d	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)					
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	40	—	V	I_C = 1mA, I_B = 0
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	40	—	V	I_C = 100μA, I_E = 0
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	4.0	—	V	I_E = 10μA, I_C = 0
Collector Cutoff Current	I_{CBO}	—	100	nA	V_{CB} = 30V, I_E = 0
Emitter Cutoff Current	I_{EBO}	—	100	nA	V_{EB} = 2V, I_C = 0
ON CHARACTERISTICS (Note 2)					
DC Current Gain	h_{FE}	30	—	—	I_C = 8mA, V_{CE} = 10.0V
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	0.5	V	I_C = 4mA, I_B = 400μA
Base-Emitter On Voltage	$V_{BE(SAT)}$	—	0.95	V	I_C = 4mA, V_{CE} = 10.0V
SMALL SIGNAL CHARACTERISTICS					
Current Gain-Bandwidth Product	f_T	400	—	MHz	V_{CE} = 10V, f = 100MHz, I_C = 8mA
Collector-Base Capacitance	C_{CB}	—	0.7	pF	V_{CB} = 10V, f = 1.0MHz, I_E = 0
Collector-Base Feedback Capacitance	C_{RB}	—	0.65	pF	V_{CB} = 10V, f = 1.0MHz, I_E = 0
Collector-Base Time Constant	Rb'Cc	—	9	ps	I_C = 4mA, V_{CB} = 10V, f = 31.8MHz

Notes:
1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch pad layout, as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
2. Short duration pulse test used to minimize self-heating effect.
3. No purposefully added lead. Halogen and Antimony Free.
4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.

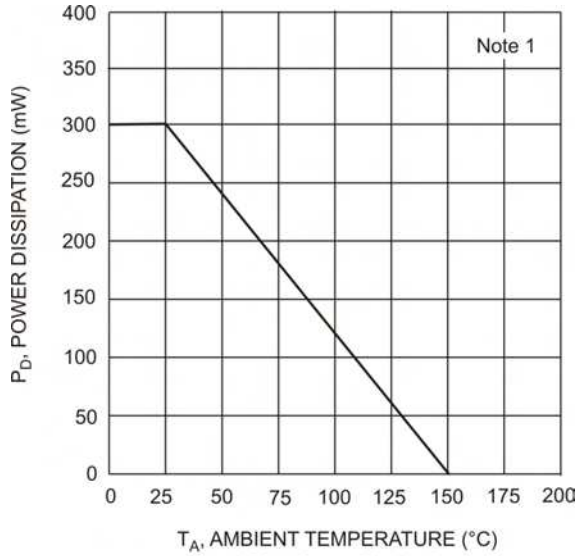


Fig. 1, Max Power Dissipation vs Ambient Temperature

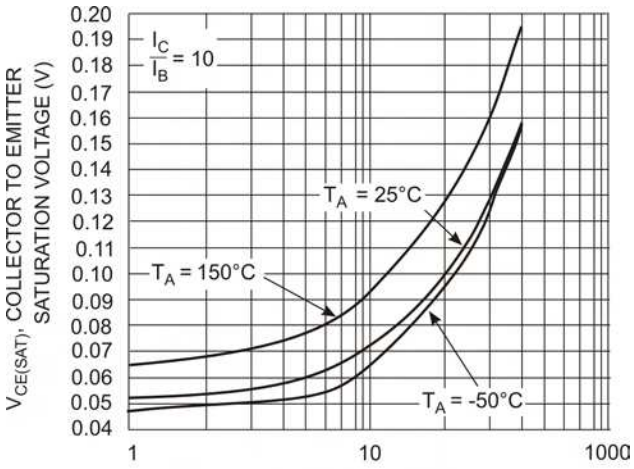


Fig. 2 Collector Emitter Saturation Voltage vs. Collector Current

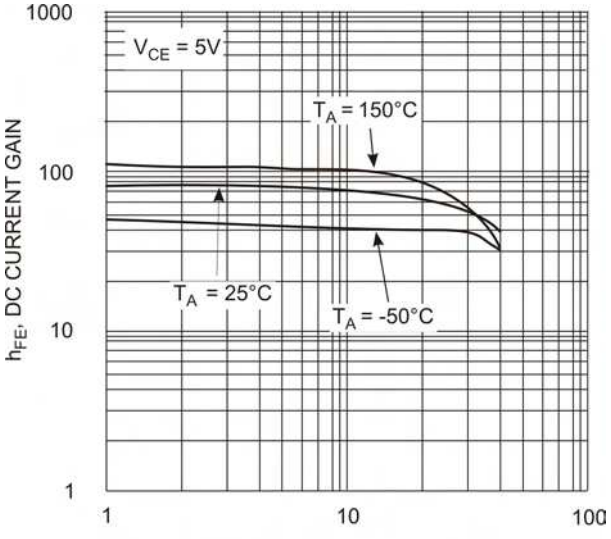


Fig. 3, DC Current Gain vs. Collector Current

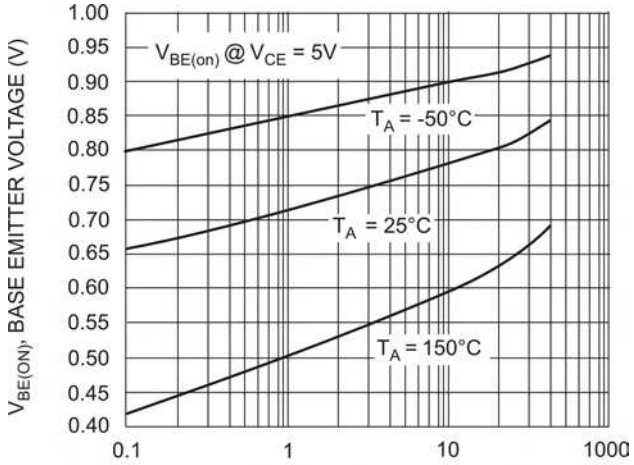


Fig. 4 Base Emitter Voltage vs. Collector Current

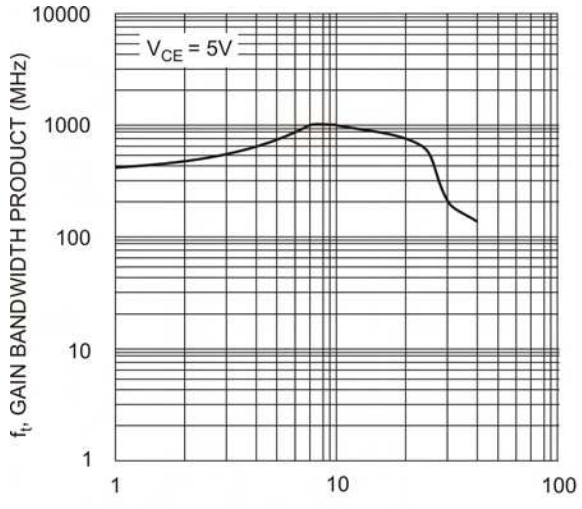


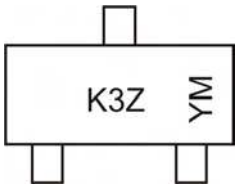
Fig. 5, Gain Bandwidth Product vs Collector Current

Ordering Information (Note 5)

Device	Packaging	Shipping
MMBTH24-7-F	SOT-23	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



K3Z = Product Type Marking Code
YM = Date Code Marking
Y = Year ex: N = 2002
M = Month ex: 9 = September

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D